

IN THE SPECIFICATION

Please replace the following paragraph beginning on page 1, line 10 with the following:

In recent years, accompanying the miniaturization of wiring in semiconductor integrated circuits, signal delay problems can occur. To solve these problems, there has ~~signal delay has arisen problems accompanying the miniaturization of wiring in semiconductor integrated circuits. In order to solve the problems of the signal delay, there~~ have been proposed a method for lowering the wiring resistance using copper as wiring material, and a method for lowering capacitance using a low-dielectric-constant film (low-k dielectric film) as an interlayer insulating film.